


- NOTES :
- MATERIAL :
 - HOUSING:LCP UL94 V-0, BLACK COLOR.
 - SHELL: STAINLESS STEEL
 - CONTACT: COPPER ALLOY
 - FINISH :
 - CONTACT: GOLD PLATING ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL AREA. 50u" MIN NICKEL PLATING OVERALL.
 - SHELL: 30u" MIN SOLDERABLE NICKEL PLATING OVERALL. GOLD FLASH ON SOLDER TAIL AREA.
 - ELECTRICAL CHARACTERISTICS:
 - OPERATING VOLTAGE : 100V AC(rms)/DC.
 - CURRENT RATING : 0.5 A.
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - CONTACT RESISTANCE: 100 m OHMS MAX.
 - INSULATION RESISTANCE: 1000M OHMS MIN. AT 250VDC.
 - DIELECTRIC WITHSTANDING VOLTAGE:500 VAC/1MINUTE.

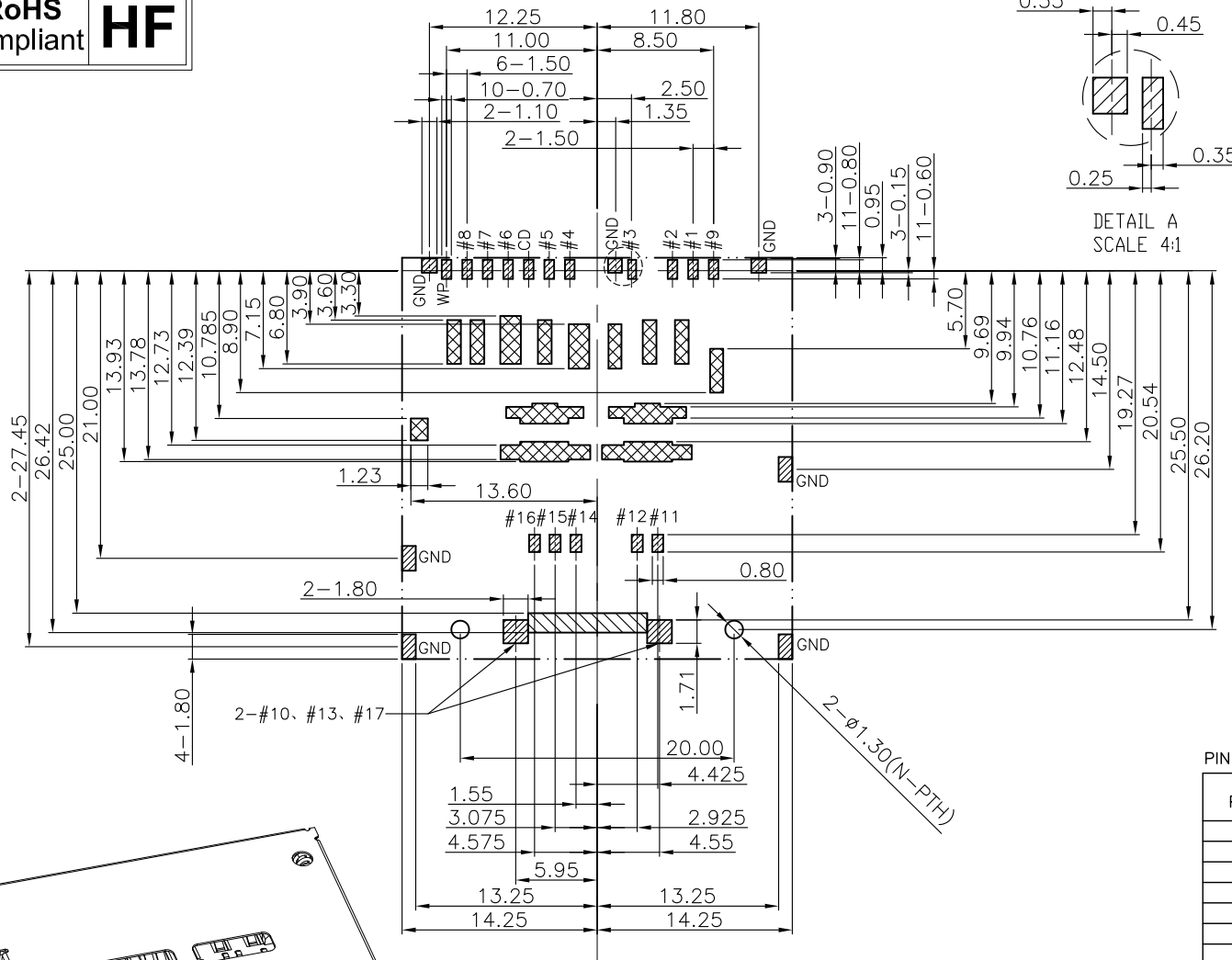
PART.NO.: TW145-AP401-**

- 08: 功能区镀金1U", 锡脚Gold Flash
- 09: 功能区镀金3U", 锡脚Gold Flash
- 10: 功能区镀金5U", 锡脚Gold Flash
- 11: 功能区镀金15U", 锡脚Gold Flash
- 12: 功能区镀金30U", 锡脚Gold Flash

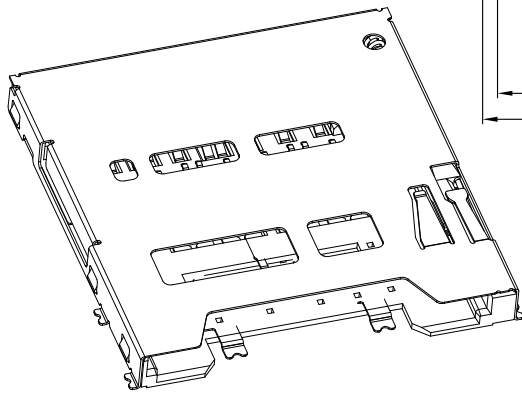
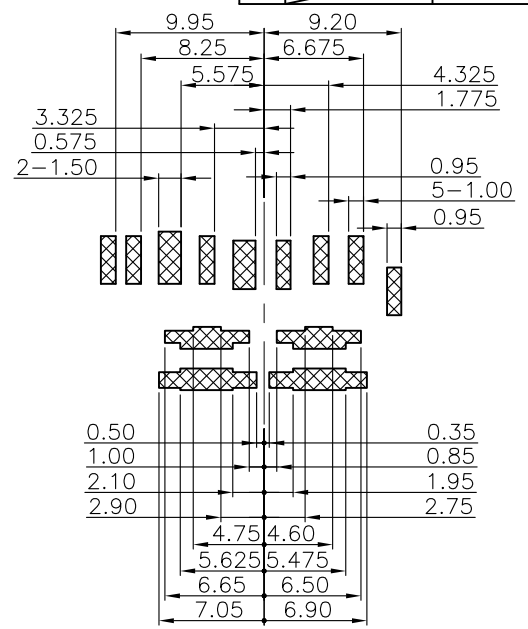
GENERAL TOLERANCE		DWG.NO.	TW145-AP401-00	PART.NO.	TW145-AP401-**	DRAWN	L.M.J 2017.09.22	UNIT	mm	SCALE	1:1
x.±0.50	x.±5°	REV.	A	TITLE	SD4.0 Push H2.90-2 conn.	CHECKED		 东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			
.x±0.25	.x±2°	SIZE		SHEET	1 OF 3	APPROVED					
.xx±0.15	.xx±1°	A4									

RoHS Compliant HF

REV.	ECN NO.	MODIFY CONTENT
A		NEW



DETAIL A
SCALE 4:1



- PAD AREA
- KEEP OUT AREA
- NO COPPER AREA (NO TRACE & VIA & GND)
- GND PATTERN ONLY

- OPEN/CLOSE OF SD SWITCH:
- CD INSETION CARD: ON
NORMAL: OFF
 - WP WRITE ENABLE: ON
WRITE PROTECTED: OFF
NORMAL: OFF

RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05mm

PIN ASSIGNMENT

PIN	SD		UHS-II		MMC	
	PIN NO	DESCRIPTION	PIN NO	DESCRIPTION	PIN NO	DESCRIPTION
P1	#9	DAT2	#9	DAT2		
P2	#1	DATA3	#1	DATA3	#1	RSV
P3	#2	CMD	#2	CMD	#2	CMD
P4	#3	VSS1	#3	VSS1	#3	VSS
P5	#4	VDD	#4	VDD	#4	VDD
P6	#5	CLK	#5	CLK	#5	CLK
P7	#6	VSS2	#6	VSS2	#6	VSS
P8	CD	CARD DETECT	CD	CARD DETECT		
P9	#7	DAT0	#7	RCLK+	#7	DAT
P10	#8	DAT1	#8	RCLK-		
P11	WP	WRITE PROTECT	WP	WRITE PROTECT		
P12			#10	UHS-II VSS3		
P13			#11	UHS-II D0+		
P14			#12	UHS-II D0-		
P15			#13	UHS-II VSS4		
P16			#14	UHS-II VDD2		
P17			#15	UHS-II D1-		
P18			#16	UHS-II D1+		
P19			#17	UHS-II VSS5		

GENERAL TOLERANCE	DWG.NO.	TW145-AP401-00	PART.NO.	TW145-AP401-***	DRAWN	L.M.J 2017.09.22
x.±0.50	REV.	A	TITLE	SD4.0 Push H2.90-2 conn.	CHECKED	
.x±0.25	SIZE	A4	SHEET	2 OF 3	APPROVED	
.xx±0.15	A4					

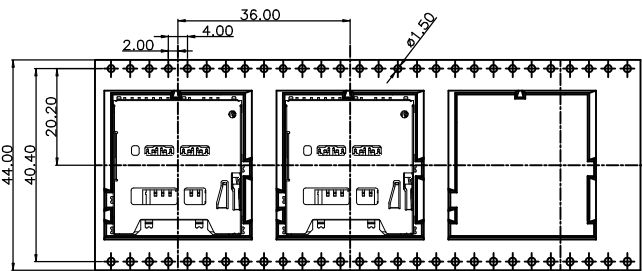
UNIT mm SCALE 1:1

OLN 东莞市欧联电子科技有限公司
DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.

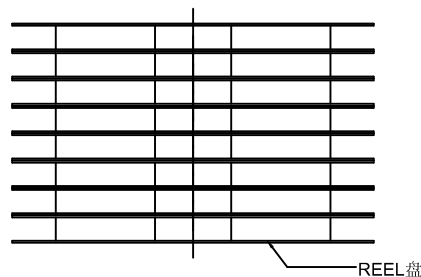
包装作业规范

包装作业图示及说明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

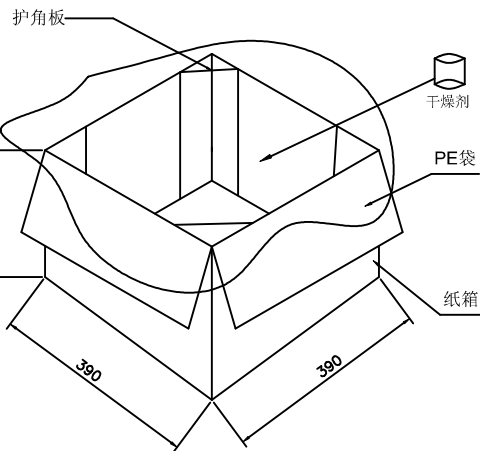
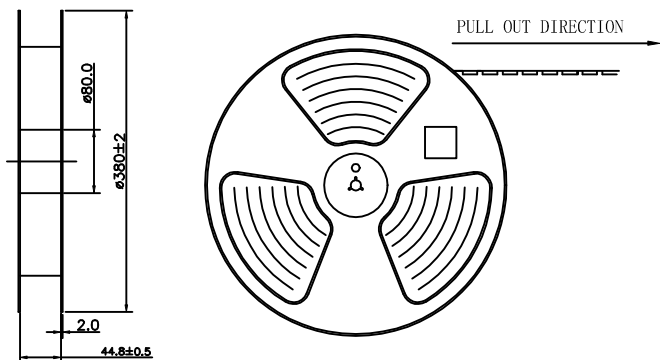
- 一.
- 1) 将成品一一放入REEL包装盘内,依同一方向放入.
 - 2) 包装时,如图所示.
 - 3) 一个REEL包装盘放置450个成品.



- 三.
- 1) 每箱装6盘REEL包装盘.
 - 2) 每箱放置2700PCS的成品.



- 二.
- 1) 装盘前先把前面空20pcs产品,然后再开始装盘,尾端也需空20pcs产品,上带加长200mm.
 - 2) 装满成品的REEL包装盘如下图所示.



- 四.
- 1) 用TAPE将纸箱封实.

备注 (REMARK)

1. 若有未装满之零数箱,必须以缓冲材塞满.

GENERAL TOLERANCE	DWG.NO.	TW145-AP401-00	PART.NO.	TW145-AP401-**	DRAWN	L.M.J 2017.09.22
x.±0.50	REV.	A	TITLE	SD4.0 Push H2.90-2 conn	CHECKED	
.x±0.25	SIZE	A4	SHEET	3 OF 3	APPROVED	
.xx±0.15						

UNIT	mm	SCALE	1:1
东莞市欧联电子科技有限公司 DONGGUAN OLN ELECTRONICS TECHNOLOGY CO., LTD.			